



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	24/10/2014
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Arcidiacono Salvatore	Representative Title	IPG IPC Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L4976DHD	A7Y7*U751BA6	A	MU1A	24/10/2014
Amount		UoM	Unit type	ST ECOPACK Grade
443.60		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	250	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	10.30 X 7.50 X 2.5	16	gull wing	
Comment	package: SO 16 .30 LARGE JEDEC MS-013			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	A7Y7*U751BA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	9.197	mg	supplier	die	Silicon (Si)	7440-21-3		8.946	mg	972708	20167
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.051	mg	5545	115
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.029	mg	3153	65
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.12	mg	13048	271
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.005	mg	544	11
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.046	mg	5002	104
Leadframe	Copper & its alloys	82.069	mg	supplier	alloy	Copper (Cu)	7440-50-8		79.946	mg	974132	180221
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		1.88	mg	22908	4238
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.113	mg	1377	255
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.098	mg	1194	221
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.029	mg	353	65
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.002	mg	24	5
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	12	2
Die attach	Other inorganic materials	1.704	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		1.278	mg	750000	2881
Die attach				supplier	glue or tape	Epoxy Cresol Novolak	29690-82-2		0.421	mg	247066	949
Die attach				supplier	glue or tape	tert-butanol	75-65-0		0.002	mg	1174	5
Die attach				supplier	glue or tape	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.003	mg	1761	7
Bonding wire	Precious metals	0.405	mg	supplier	wire	Gold (Au)	7440-57-5		0.405	mg	1000000	913
encapsulation	Other Organic Materials	350.225	mg	supplier	mold compound	Silica, vitreous	60676-86-0		280.179	mg	799997	631603
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		24.515	mg	69998	55264
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		14.009	mg	40000	31580
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		21.014	mg	60001	47372
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		4.203	mg	12001	9475
encapsulation				JIG I	mold compound	Brominated Epoxy Resin	40039-93-8		5.254	mg	15002	11844
encapsulation				supplier	mold compound	Carbon black	1333-86-4		1.051	mg	3001	2369